

SOT1136-1

plastic ball grid array package; 420 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA420
Package type industry code	BGA420
Package style descriptive code	BGA (ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	144E
JEDEC package outline code	MS-034
JEITA package outline code	- - -
Mounting method type	S (surface mount)
Issue date	20-5-2009

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	22.8	-	23	23.2	mm
E	package width	22.8	-	23	23.2	mm
A	seated height	1.8	-	2.03	2.25	mm
A ₂	package height	1.4	-	1.53	1.65	mm
e	nominal pitch	-	-	1	-	mm
n ₂	actual quantity of termination	-	-	420	-	



2. Package outline

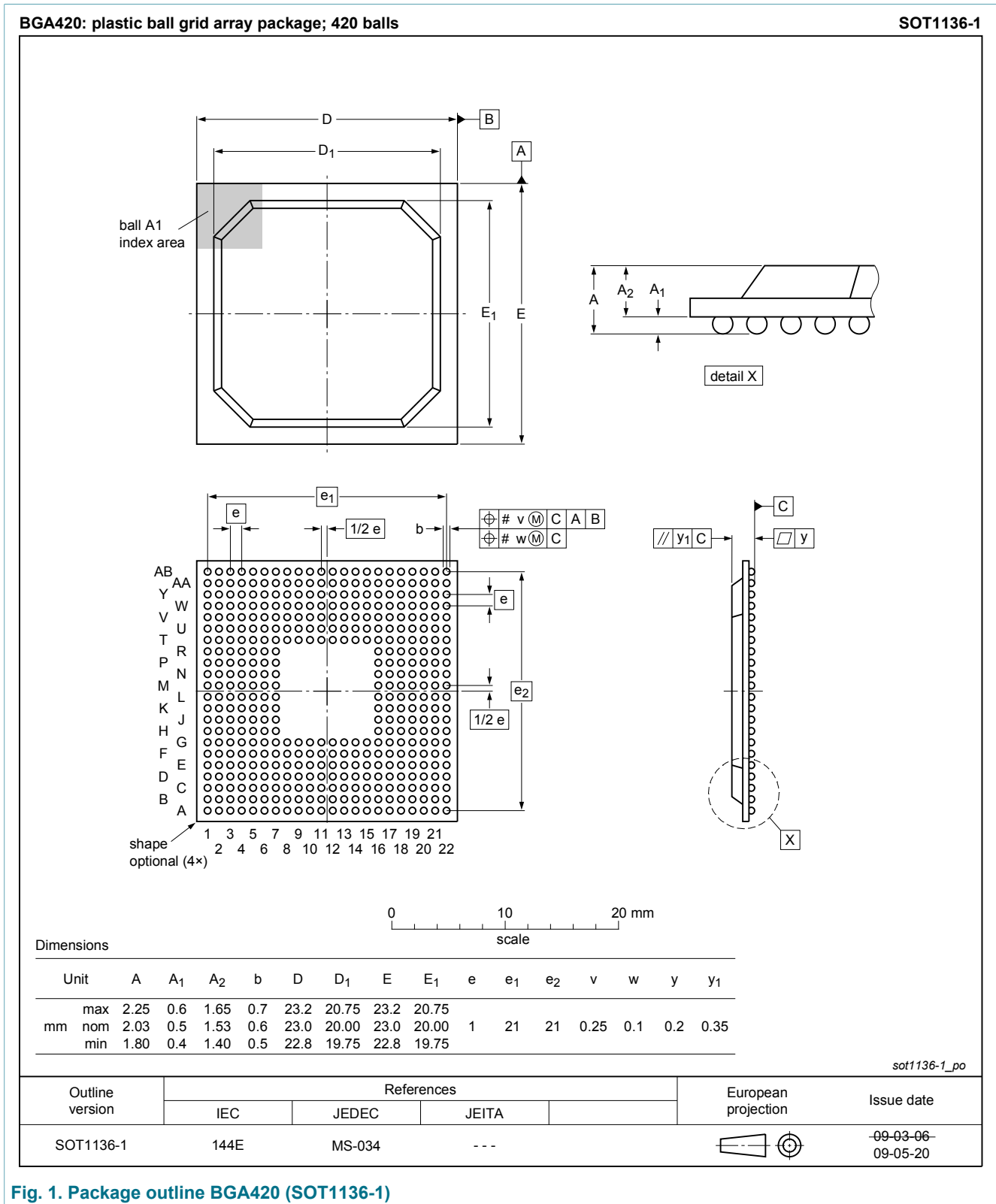


Fig. 1. Package outline BGA420 (SOT1136-1)

3. Legal information

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